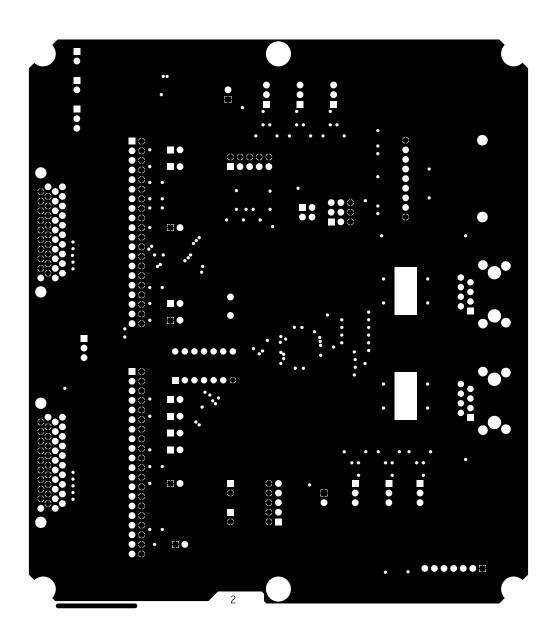
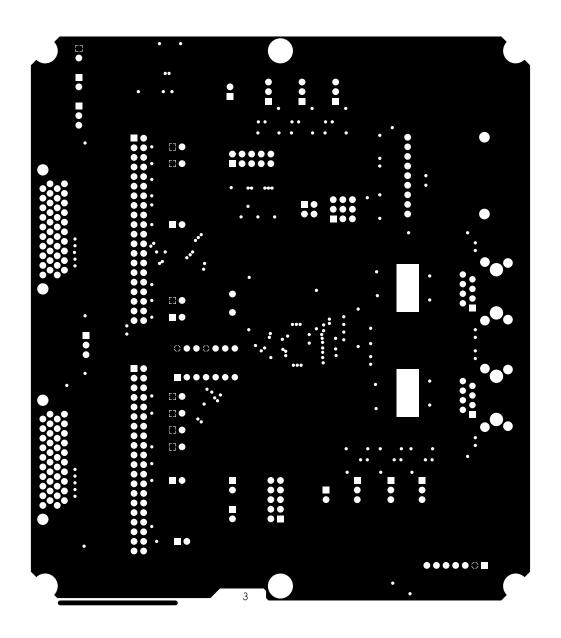


•1	ALL ARTWORK VIEWED FROM TOP SIDE DATE: DECEMBER 16, 2005)
National Semiconductor	BOARD NAME:DP83849 DUAL PHYTER DEMO II BOARD NO: 880012704-001 R	EV B
INTERFACE DIVISION	LAYER NAME: TOP ETCH LAYER NO: 1 SHEET 1 of 8	



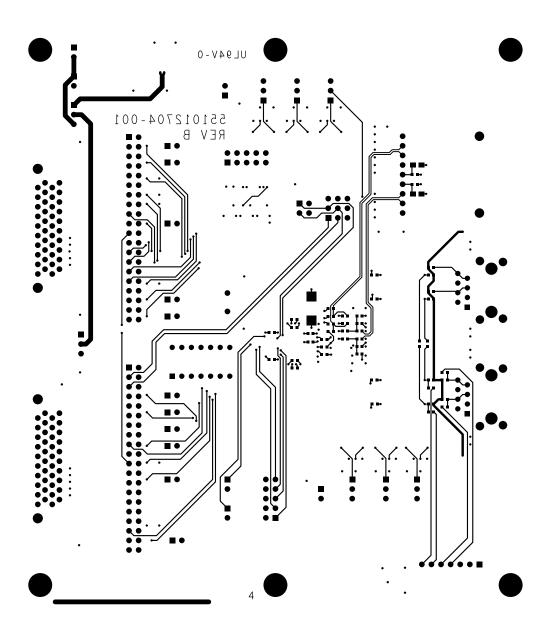
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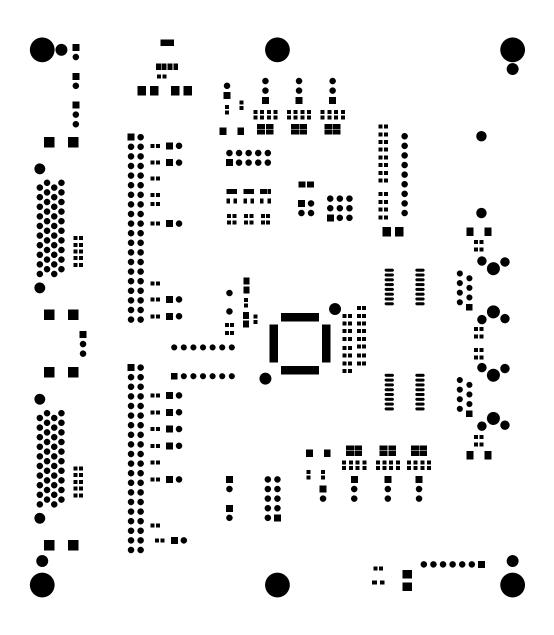


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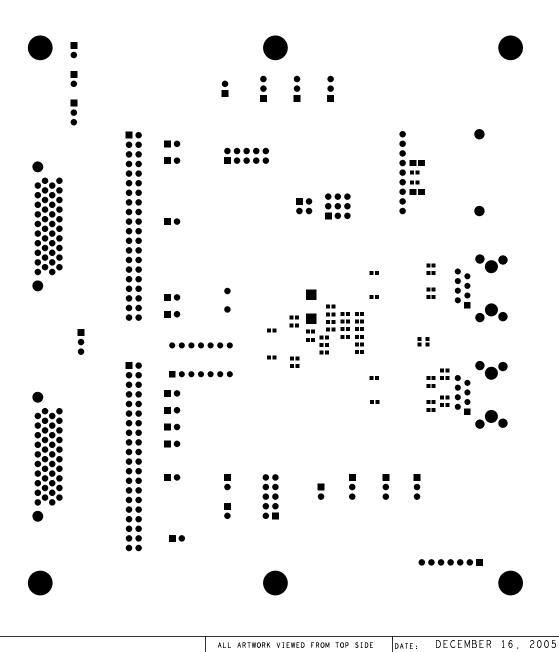


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INTERFACE DIVISION	LAYER NAME: BOTTOM ETCH LAYER NO: 4 SHEET 4 of 8	

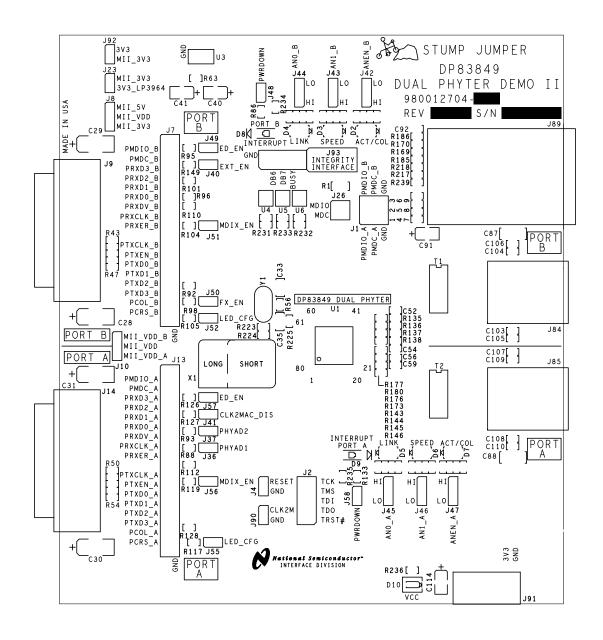


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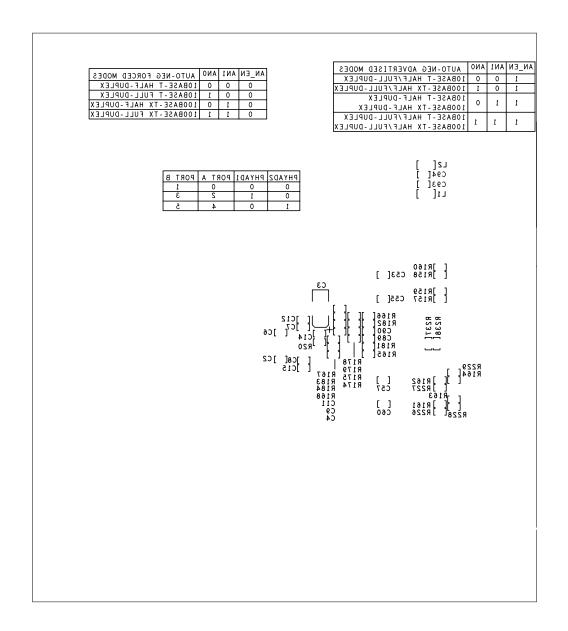


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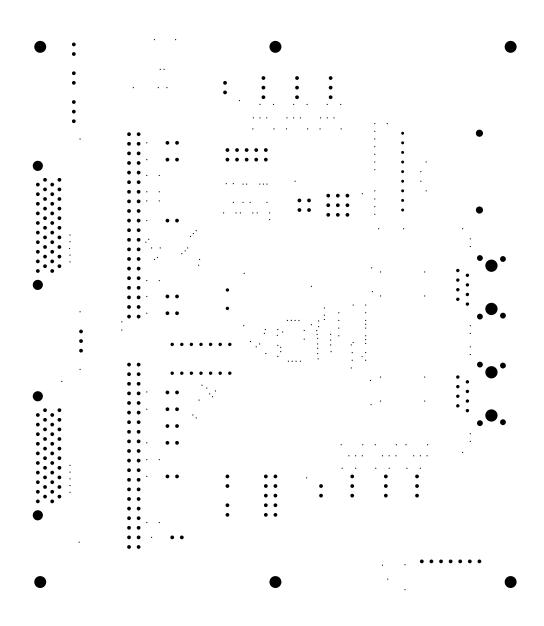
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LAYER	NAME: BOTTOM SILKSCREEN	LAYER NO: SHEET 8 of 8	



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